

Resource Summary Report

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Oxford: PlasmaPro 100 RIE Plasma Technology

RRID:SCR_020376

Type: Tool

Proper Citation

Oxford: PlasmaPro 100 RIE Plasma Technology (RRID:SCR_020376)

Resource Information

URL: <https://plasma.oxinst.com/products/rie/plasmapro-100>

Proper Citation: Oxford: PlasmaPro 100 RIE Plasma Technology (RRID:SCR_020376)

Description: PlasmaPro 100 RIE modules deliver anisotropic dry etching. Being compatible with all wafer sizes up to 200mm, it has rapid change between wafer size, uniformity, high throughput and high precision processes, in situ chamber cleaning and end pointing, and wide temperature range electrode, from 150 degrees C to 400 degrees C.

Resource Type: instrument resource

Keywords: Oxford, Plasma Technology, Instrument, Resource equipment, Equipment, USEDit,

Availability: Commercially available

Resource Name: Oxford: PlasmaPro 100 RIE Plasma Technology

Resource ID: SCR_020376

Alternate IDs: Model_Number_100_RIE

Record Creation Time: 20220129T080350+0000

Record Last Update: 20260912T195935+0000

Ratings and Alerts

No rating or validation information has been found for Oxford: PlasmaPro 100 RIE Plasma Technology.

No alerts have been found for Oxford: PlasmaPro 100 RIE Plasma Technology.

Data and Source Information

Source: [SciCrunch Registry](#)

Usage and Citation Metrics

We have not found any literature mentions for this resource.